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EP-01-002

April 30, 2004

To: Commissioner for Patents  
P.O.Box 1450  
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/781,022 02/17/04 |  
Hsi Mao Hsiao  
METHOD TO IMPROVE BORDERLESS METAL  
LINE PROCESS WINDOW FOR SUB-MICRON  
DESIGNS  
| \_\_\_\_\_ |

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
mail in an envelope addressed to: Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450, on May 4, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date Stephen B. Ackerman 5/4/04

EP-01-002

U.S. Patent 6,077,770 to Hsu, "Damascene Manufacturing Process Capable of Forming Borderless Via," discloses a damascene borderless interconnect process.

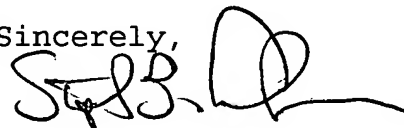
U.S. Patent 5,578,166 to Hirota, "Method of Reactive Ion Etching of a Thin Copper Film," discloses an ion etch of a Cu film.

U.S. Patent 6,057,230 to Liu, "Dry Etching Procedure and Recipe for Patterning of Thin Film Copper Layers," discloses a dry etch for thin Cu layers.

U.S. Patent 5,880,015 to Hata, "Method of Producing Stepped Wall Interconnects and Gates," discloses a stepped interconnect etch process.

U.S. Patent 5,937,326 to Cho, "Method for Making Semiconductor Device Having Via Hole," discloses a method for making a semiconductor device having a via hole.

Sincerely,

A handwritten signature in black ink, appearing to read 'S.B. Ackerman', with a long horizontal flourish extending to the right.

Stephen B. Ackerman,  
Reg. No. 37761

Form PTO-1449

INFORMATION DISCLOSURE CITATION  
IN AN APPLICATION

(Use several sheets if necessary)

MAY 06 2004

TRADEMARK OFFICE

Docket Number (Optional)

EP-01-002

Application Number

10/781,022

Applicant

Hsi Mao Hsiao

Filing Date

02/17/04

Group A1 UMI

## U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	PURCH DATE IF APPROPRIATE
	6077770	6/20/00	Hsu	438	622	10/30/98
	5578166	11/26/96	Hirota	156	643.1	5/24/95
	6057230	5/2/00	Liu	438	637	9/17/98
	5880015	3/9/99	Hata	438	585	10/14/94
	5937326	8/10/99	Cho	438	669	5/30/96

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

## OTHER DOCUMENTS (Including Author, Title, Date, Portmox Pages, Etc.)


EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.